

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE


|                  |                               |   |                                |
|------------------|-------------------------------|---|--------------------------------|
| Applicants:      | Sang Jun Youn, et al.         | § |                                |
|                  |                               | § | Group Art Unit: 1772           |
| Application No.: | 10/599,523                    | § |                                |
|                  |                               | § | Examiner: Ducheneaux, Frank D. |
| Filed:           | September 29, 2006            | § |                                |
|                  |                               | § | Confirmation No.: 1302         |
| For:             | THERMOPLASTIC COMPOUND PLATE- | § |                                |
|                  | SHAPED MATERIAL, METHOD FOR   | § |                                |
|                  | MANUFACTURING AND ARTICLES    | § |                                |
|                  | MANUFACTURED USING THE SAME   | § |                                |

Mail Stop: Amendment  
 Commissioner for Patents  
 PO Box 1450  
 Alexandria, VA 22313-1450

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**CERTIFICATE OF EFS-WEB TRANSMISSION**

Pursuant to 37 C.F.R. §1.8, I hereby certify that this correspondence is being electronically submitted to the U.S. Patent and Trademark Office website, [www.uspto.gov](http://www.uspto.gov), on 8-20-09.

  
 Susan Caglagis

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**RESPONSE TO RESTRICTION REQUIREMENT**

Sir:

Responsive to the Restriction Requirement in the Office Action mailed March 20, 2009, having a shortened statutory period for response expiring April 20, 2009, pursuant to the above-referenced application, Applicants elect without traverse Group I consisting of claims 1-10 drawn to a product. Applicants reserve the right to refile the non-elected claims in one or more divisional applications at a later time.

A **Listing of Claims** begins on page 2 of this paper.

**Remarks** begin on page 9 of this paper.